PRESS RELEASE

Applied Materials to Increase its Strategic Investment in BE Semiconductor Industries

Duiven, the Netherlands, October 27, 2026 - BE Semiconductor Industries N.V. (the "Company" or "Besi") (Euronext Amsterdam: BESI; OTC markets: BESIY), a leading manufacturer of assembly equipment for the semiconductor industry, acknowledged today the press release from Applied Materials, Inc. ("Applied") in which Applied announced on October 26, 2026, an increase in its strategic share ownership to approximately 20% of Besi's outstanding shares.

According to Applied's press release, Applied views its investment in Besi as long-term. Applied does not intend to seek board representation at Besi, nor does it currently have plans to purchase additional shares of Besi.

Besi and Applied have collaborated together since 2020 on the development and commercialization of integrated hybrid bonding production systems for leading semiconductor manufacturers. The collaboration brings together Applied's expertise in front-end manufacturing and Besi's leading technologies in die placement, interconnect and assembly solutions. Recently, the companies have expanded their collaboration with Besi joining Applied's EPIC Center as an Innovation Partner. Areas of collaboration target next-generation 3D IC scaling, logic and memory integration, the scaling of thermo-compression bonding and new die-on-wafer, die-on-die and die-on-panel integration platforms.

Richard W. Blickman, Besi's Chief Executive Officer, commented:
"We welcome Applied's increased strategic investment as further confirmation of Besi's hybrid bonding and wafer-level assembly strategy. It also highlights future areas of potential collaboration between the companies targeting next generation AI and photonics systems for the industry's leading customers."

About Besi
Besi is a leading manufacturer of assembly equipment supplying a broad portfolio of advanced packaging solutions to the semiconductor and electronics industries. We offer customers high levels of accuracy, reliability and throughput at a lower cost of ownership with a principal focus on wafer level and substrate assembly solutions. Customers are primarily leading semiconductor manufacturers, foundries, assembly subcontractors and electronics and industrial companies. Besi's ordinary shares are listed on Euronext Amsterdam (symbol: BESI). Its Level 1 ADRs are listed on the OTC markets (symbol: BESIY) and its headquarters are located in Duiven, the Netherlands. For more information, please visit our website at www.besi.com.

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